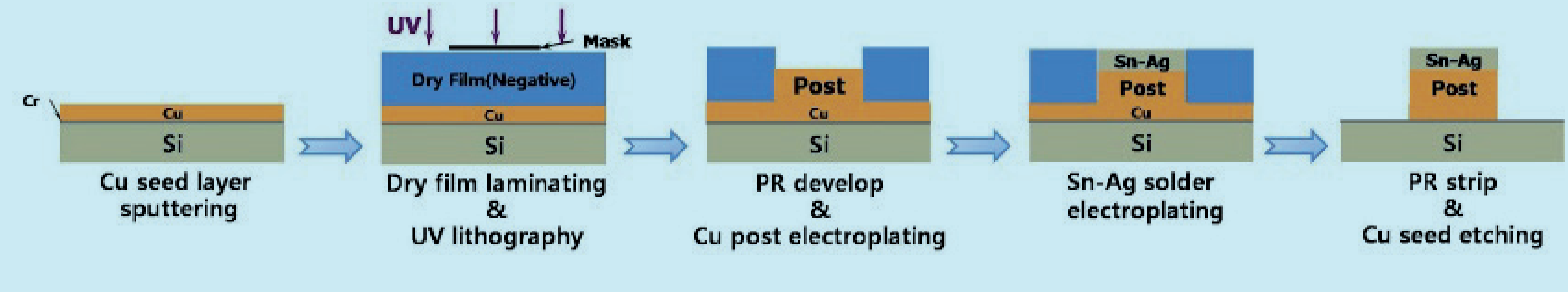
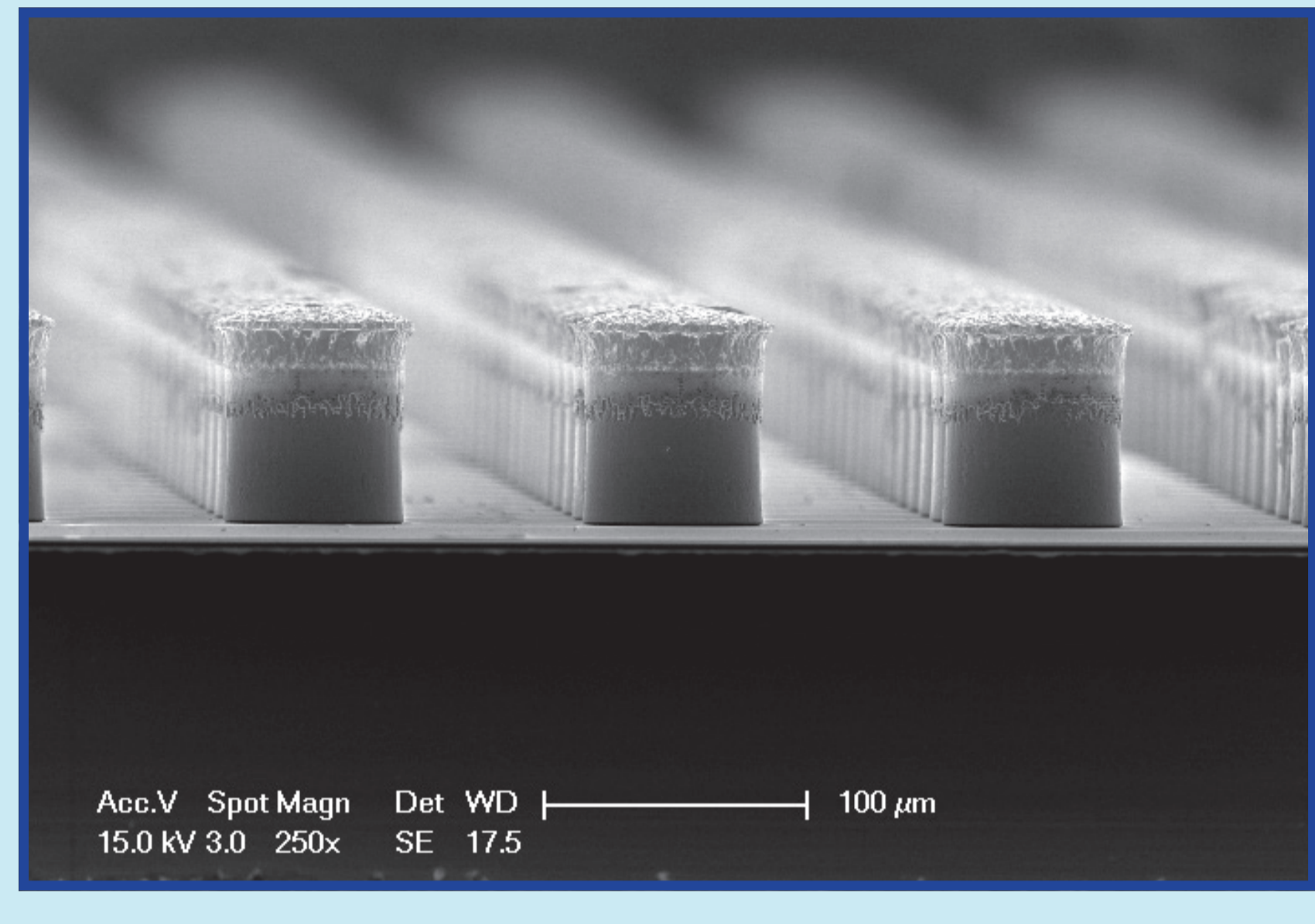
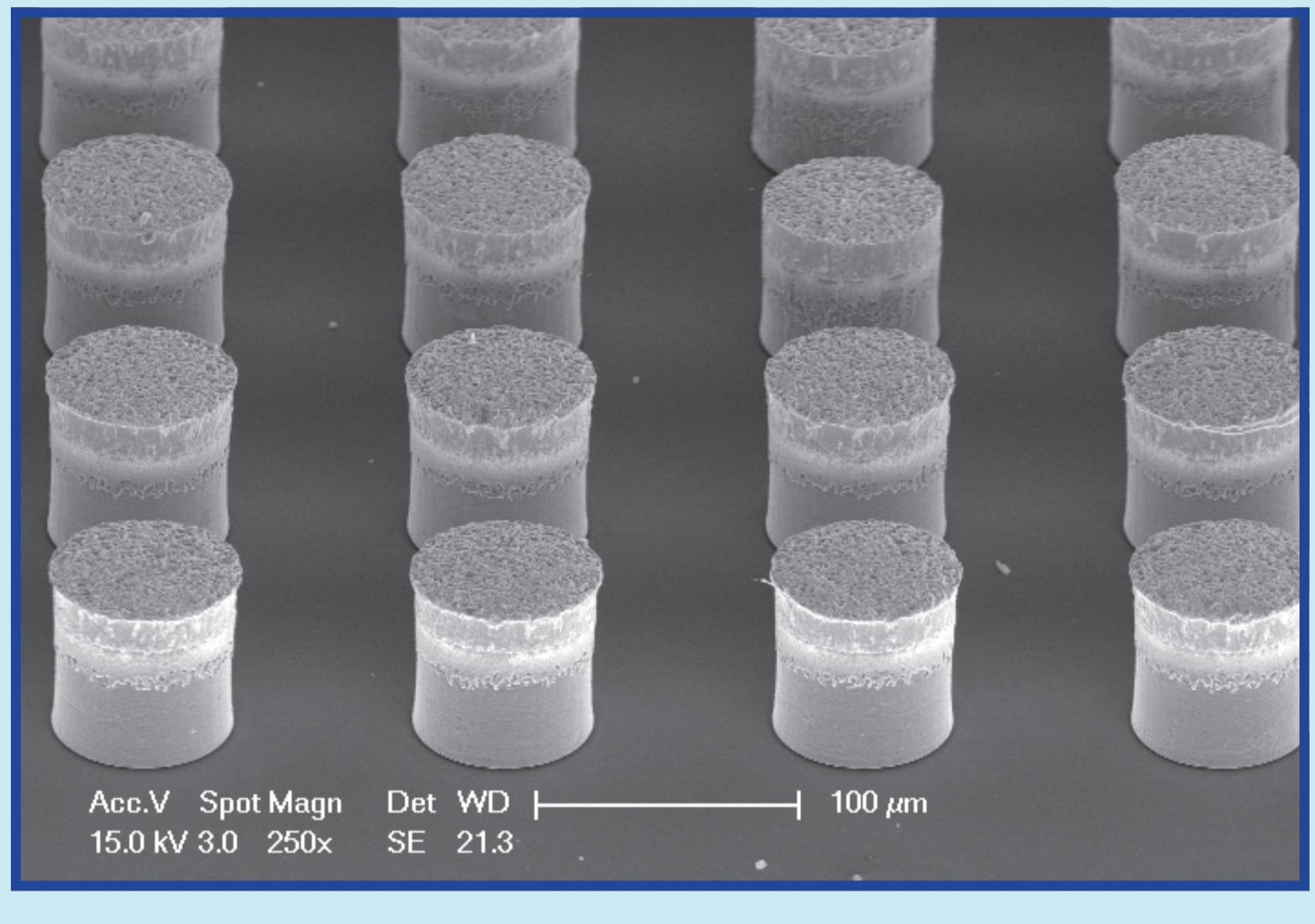
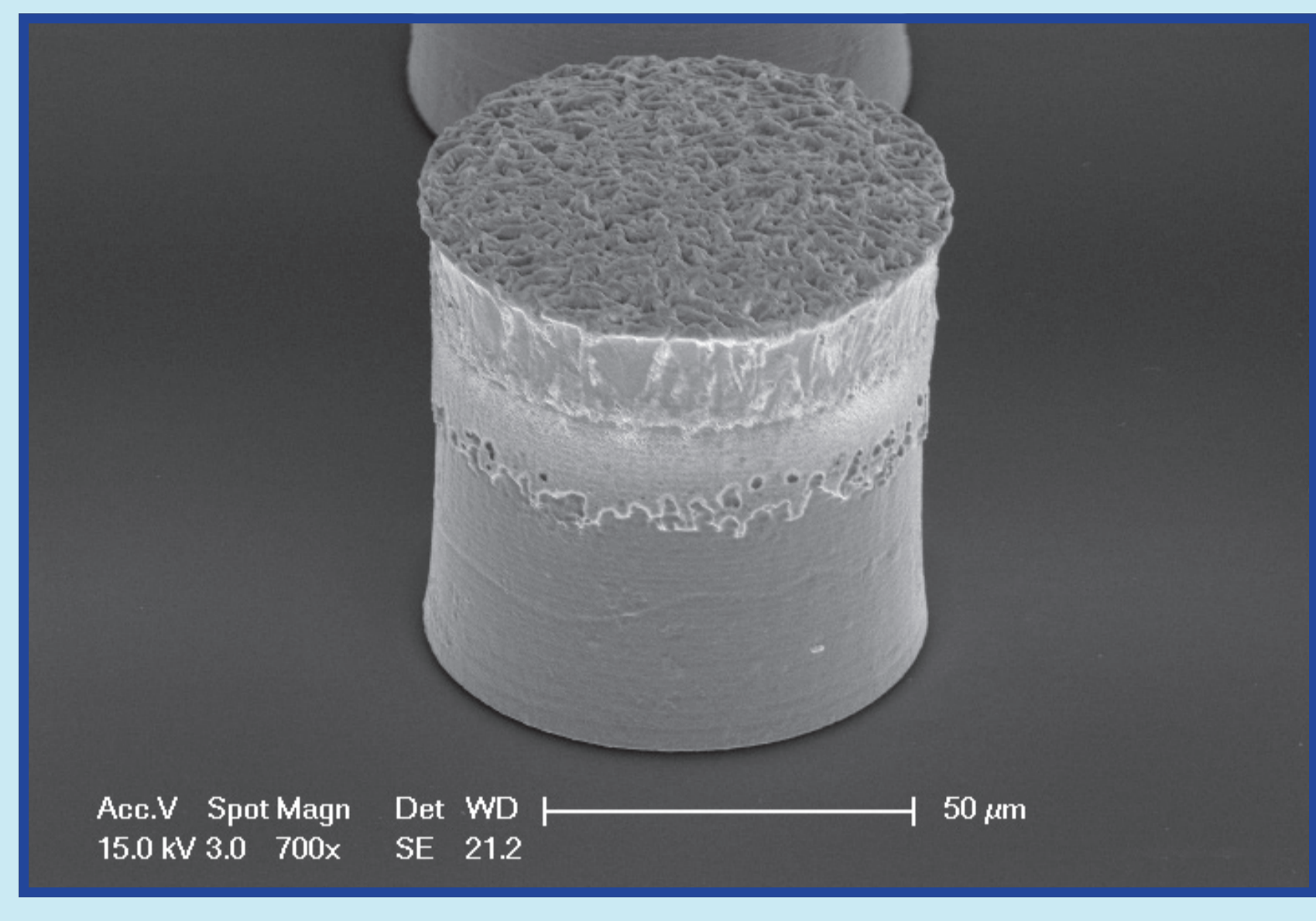
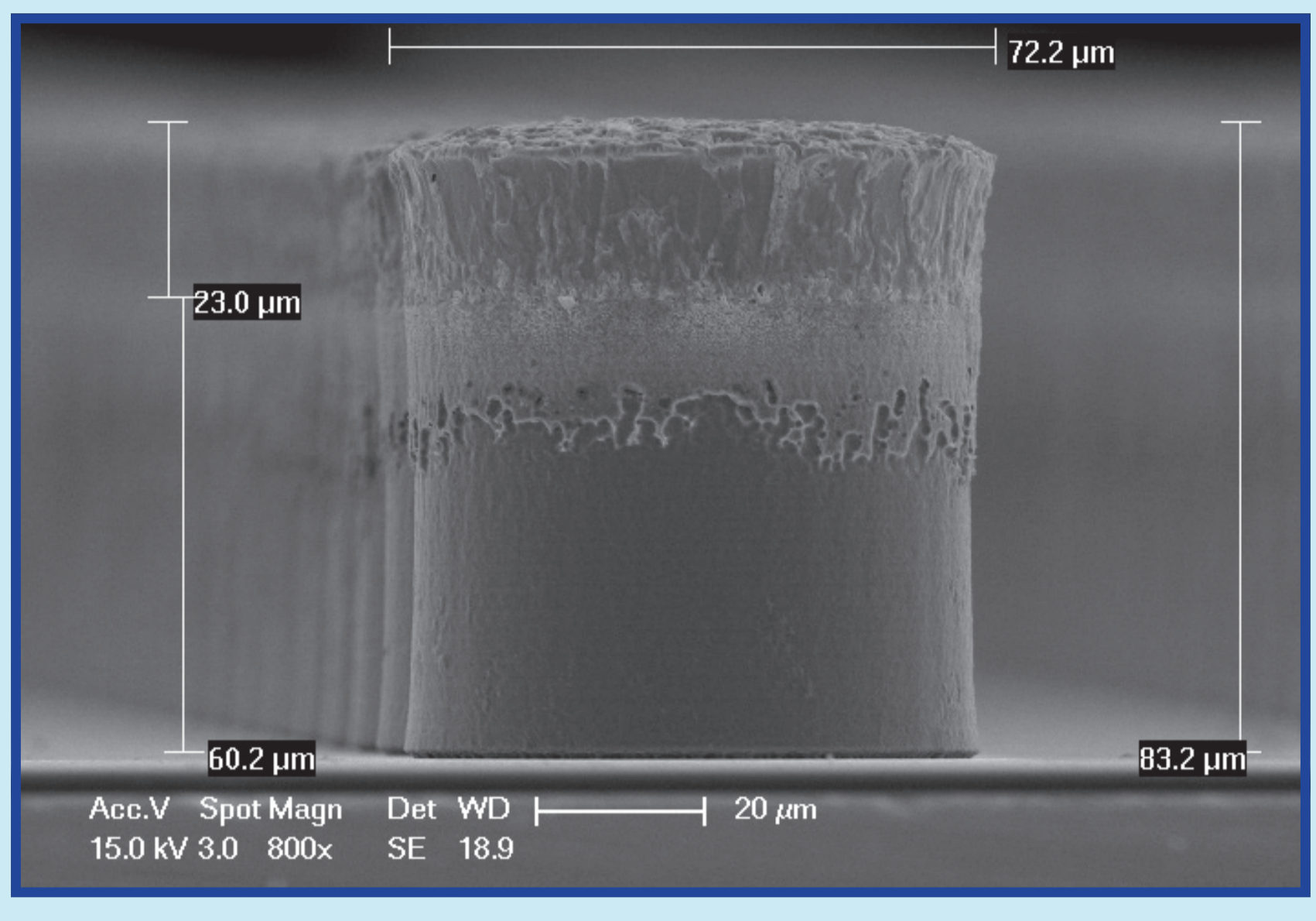


CPBT



CPBT® (Copper Post Bump TEG)

TEG (Test Element Group) Wafer is a test wafer used to determine the operation of chips .
 It is possible to produce evaluation TEG wafers according to the desired designs of customers, which are necessary for PKG development, mounting method development, sample and inspection equipment development, material development, and more.
 TEG wafers can be produced in a bump form by depositing SnAg plating for soldering on Copper post-shaped fillers that can accommodate fine pitches.
 Additionally, it is possible to include the RDL process for electrical evaluation during production.

